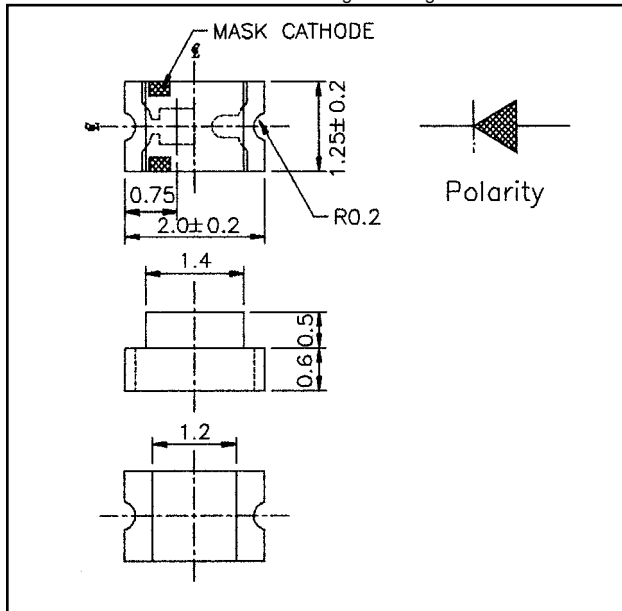




Weight: 2.0 mg Unit: mm



AND4BC

InGaN Ultra Bright Blue Chip LEDs

Features

- Package in 8mm tape on 7: dia. reel
 - Compatible with automatic placement equipment
 - Suitable for infrared and vapor phase reflow solder process
 - Mono-color type
 - Suitable for automotive backlighting, Flat backlighting for LDC, switch and symbol, indicator and backlighting for telecommunication use
- **RoHS Compliant**

Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Rating	Unit
Forward Current	I_F	30	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_D	120	mW
Operating Temp. Range	T_{Opr}	-40 to 80	$^\circ\text{C}$
Storage Temp. Range	T_{Stg}	-40 to 90	$^\circ\text{C}$

Product specifications contained herein may be changed without prior notice. It is therefore advisable to contact Purdy Electronics before proceeding with the design of equipment incorporating this product.

Electro-Optical Characteristics ($T_a = 25^\circ\text{C}$)

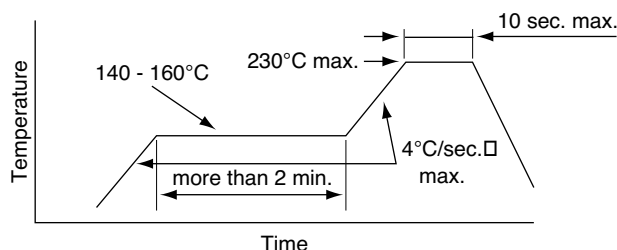
Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V_F	$I_F = 20 \text{ mA}$	-	3.5	4.3	V
Reverse Current	I_R	$V_R = 5 \text{ V}$	-	-	50	μA
Luminous Intensity	I_V	$I_F = 20 \text{ mA}$	30	50	-	mcd
Peak Emission Wavelength	I_P	$I_F = 20 \text{ mA}$	-	468	-	nm
Spectral Line Half Width	$\Delta\lambda$	$I_F = 20 \text{ mA}$	-	35	-	nm
Dominant Wavelength	λ_d	$I_F = 20 \text{ mA}$	-	470	-	nm
Full Viewing Angle	$2\theta_{1/2}$	$I_F = 20 \text{ mA}$	-	140	-	degree

Precaution

Please be careful of the following:

1. Manual soldering: maximum temperature of iron tip: 260°C max.
Soldering time: within 5 sec. per solder-land
Soldering portion of lead: up to 1.6 mm from the body of the device
2. Reflow solder: recommended condition is as follows:

3. Absolute secure counter measures against static electricity and surge should be taken when handling these products. It is recommended to use wrist band or antistatic gloves when handling these LEDs.



For reflow soldering

